

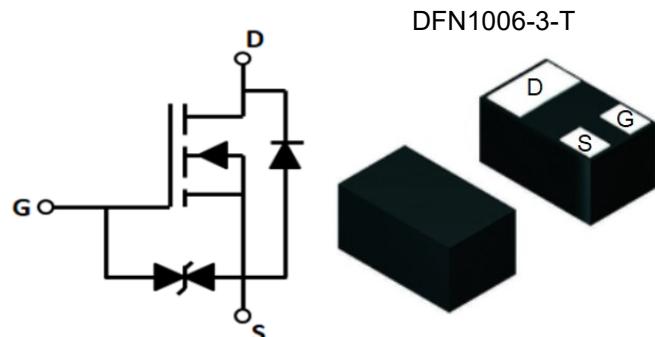
Description

CM1602S is the N-Channel enhancement mode power field effect transistors with high cell density, trench technology. This high density process and design have been optimized switching performance and especially tailored to minimize on-state resistance.

Features

- V_{DS}: 20V
- I_D: 0.9A
- R_{DS(on)} (@V_{GS}=4.5V) : < 250mΩ
- R_{DS(on)} (@V_{GS}=2.5V) : < 350mΩ
- High density cell design for extremely low R_{DS(on)}
- Excellent on-resistance and DC current capability

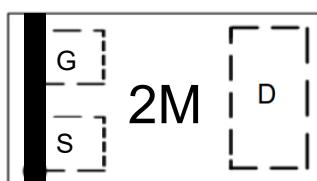
Equivalent Circuit and Pin Configuration



Applications

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Portable Instrumentation
- Load switch

Marking Information



Device Code = 2M

Ordering Information

Part Number	Packaging	Reel Size
CM1602S	10000/Tape & Reel	7 inch

Absolute Maximum Ratings (TA=25 °C unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-source Voltage	V _{DS}	20	V
Gate-source Voltage	V _{GS}	±10	V
Continuous Drain Current	I _D	1	A
		0.9	A
		0.69	A
Pulsed Drain Current ⁽¹⁾	I _{DM}	4.0	A
Total Power Dissipation @ TA=25°C ⁽²⁾	P _D	430	mW
		340	
Thermal Resistance Junction-to-Ambient ⁽²⁾	R _{θJA}	294	°C/W
		366	
Junction and Storage Temperature Range	T _{J,TSTG}	-55 to +150	°C

Electrical Characteristics (T_J=25 °C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V, I _D =250μA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _D =20V, V _{GS} =0V, T _C =25°C		1		μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V, V _D =0V			±10	uA
Gate Threshold Voltage	V _{GS(th)}	V _D =V _{GS} , I _D =250μA	0.35	0.75	1.1	V
Static Drain-Source on-Resistance	R _{D(on)}	V _{GS} =4.5V, I _D =0.5A		170	250	mΩ
		V _{GS} =2.5V, I _D =0.3A		225	350	
Diode Forward Voltage	V _{SD}	I _S =0.9A, V _{GS} =0V			1.2	V
Maximum Body-Diode Continuous Current	I _S				0.9	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _D =16V, V _{GS} =0V, f=1MHz		50		pF
Output Capacitance	C _{oss}			9		
Reverse Transfer Capacitance	C _{rss}			6		
Switching Parameters						
Turn-on Delay Time	t _{D(on)}	V _{GS} =4.5V, V _D =10V, I _D =0.5A, R _{GEN} =10Ω		6.7		ns
Turn-on Rise Time	t _r			4.8		
Turn-off Delay Time	t _{D(off)}			17.3		
Turn-off Fall Time	t _f			7.4		

Noted: (1) Pulse Test: Pulse Width≤300us, Duty cycle ≤2%.

(2) Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6cm².

Typical Performance Characteristics

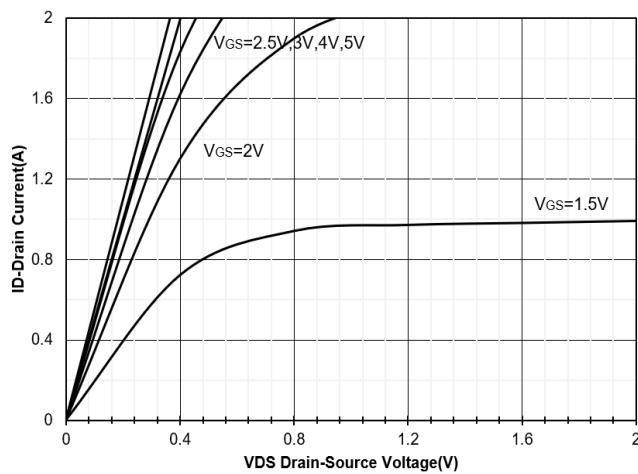


Figure 1. Output Characteristics

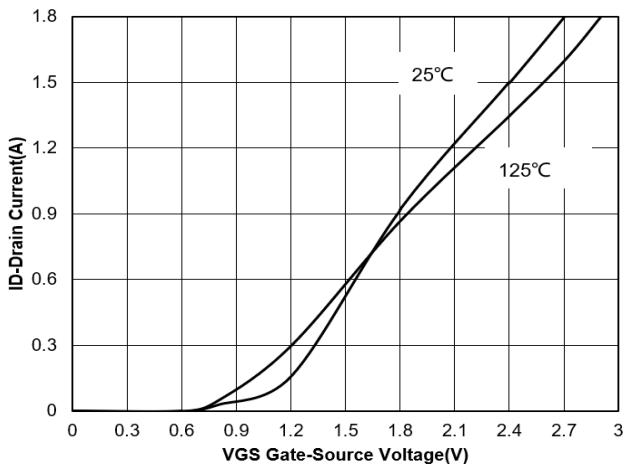


Figure 2. Transfer Characteristics

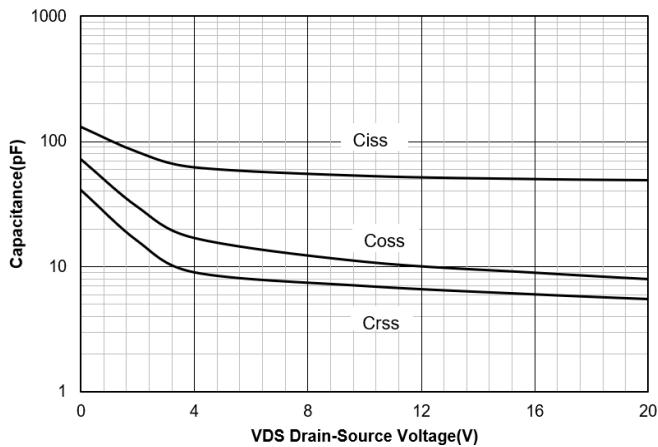


Figure 3. Capacitance Characteristics

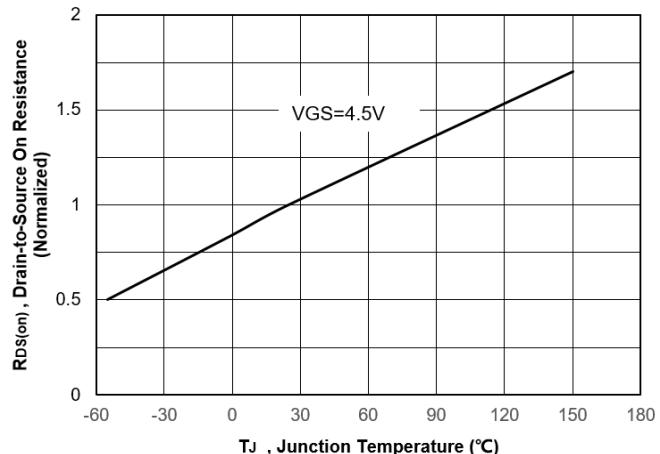


Figure 4. Normalized On-Resistance
Vs. Temperature

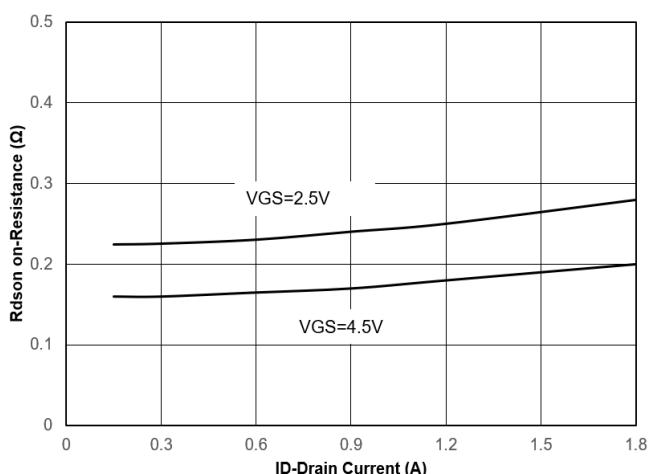


Figure 5. Drain-Source on Resistance

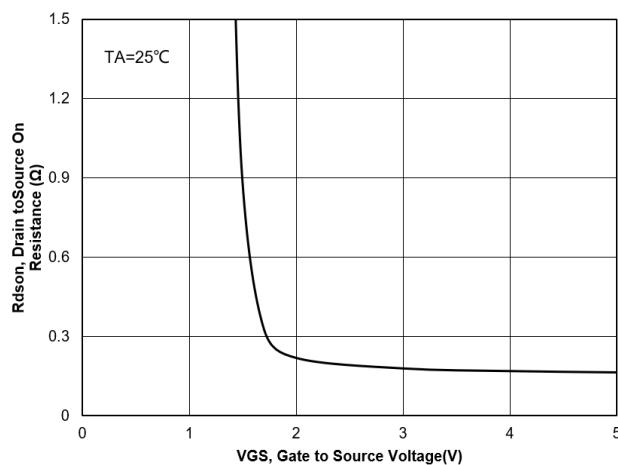


Figure 6. Typical Drain to Source ON Resistance
VS Gate Voltage and Drain Current

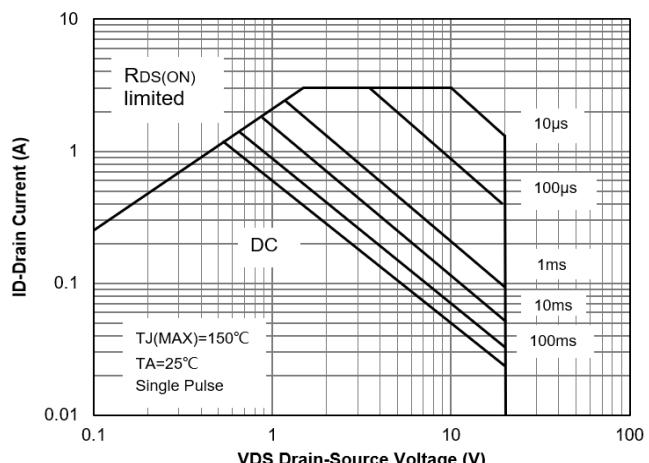


Figure 7. Safe Operation Area

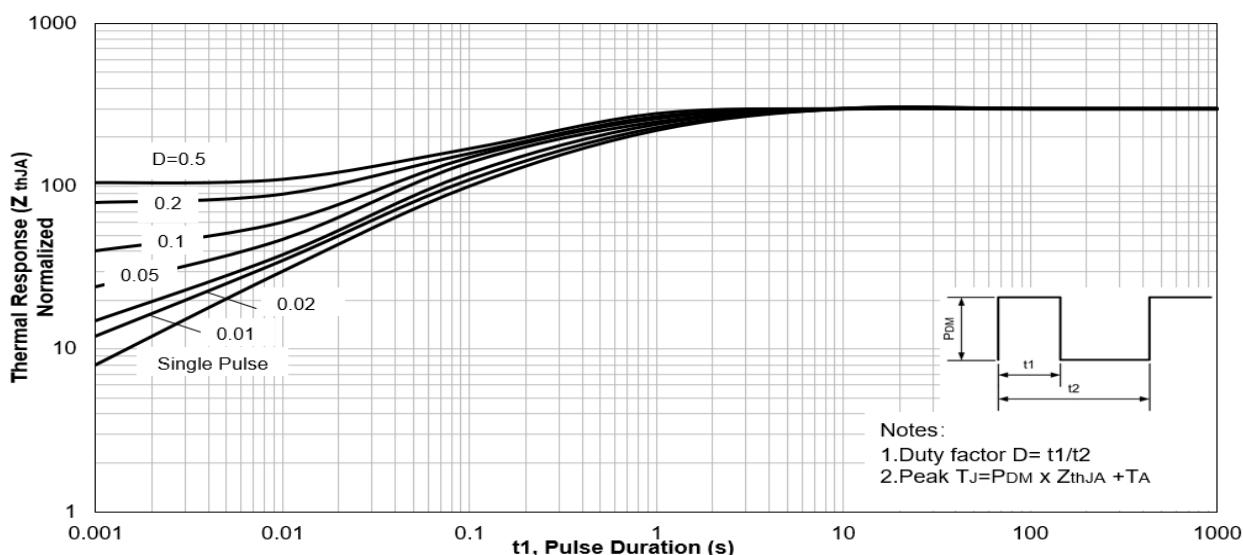


Figure 8. Maximum Effective Transient Thermal Impedance ,Junction-to-Ambient

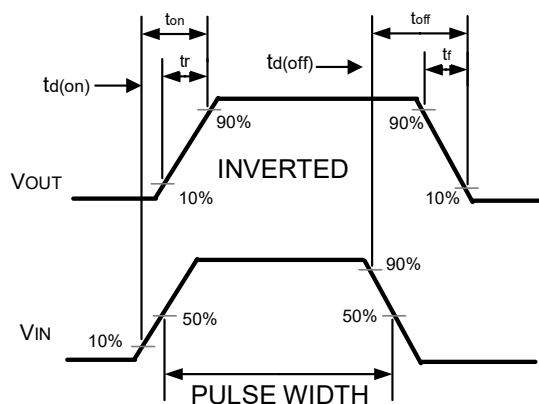
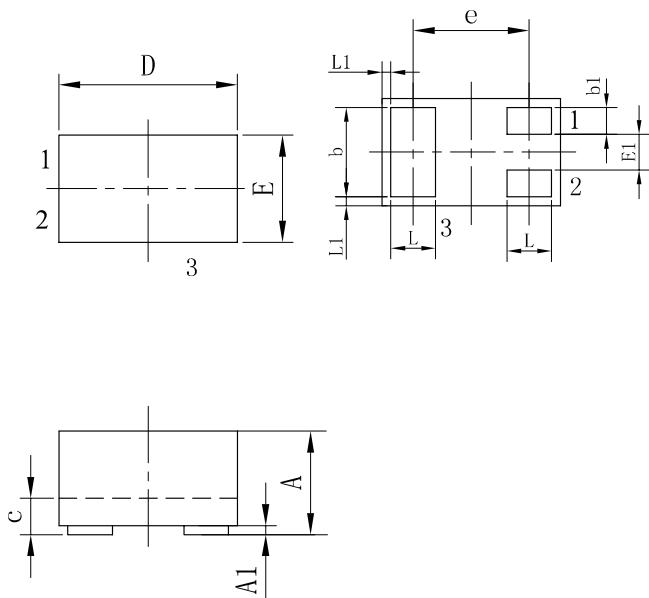


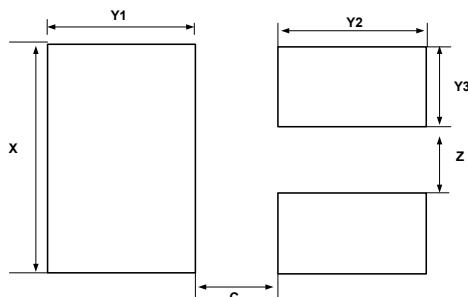
Figure 9. Switching wave

DFN1006-3-T Package Outline Drawing



SYM	DIMENSIONS					
	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.34	--	0.40	0.013	--	0.016
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.45	0.50	0.55	0.018	0.020	0.022
b1	0.10	0.15	0.20	0.004	0.006	0.008
c	0.12	0.15	0.18	0.005	0.006	0.007
D	0.95	1.00	1.05	0.037	0.039	0.041
e	0.65 BSC			0.026 BSC		
E	0.55	0.60	0.65	0.022	0.024	0.026
E1	0.15	0.20	0.25	0.006	0.008	0.010
L	0.20	0.25	0.30	0.008	0.010	0.012
L1	0.05 REF			0.0002 REF		

Suggested Land Pattern



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
C	0.25	0.010
X	0.65	0.024
Y1	0.50	0.020
Y2	0.50	0.020
Y3	0.25	0.010
Z	0.20	0.008

Contact Information

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